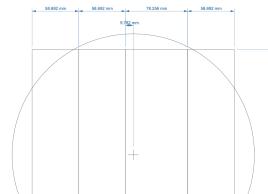
- ITS3
 - paper on «microITS3»
 - Discussion in Krakow with Bodgan and S.Masciocchi
 - Bogdan, Gianfranco and Shyam will call for an internal meeting (after the 18th of November), within GSI and Bari teams, to answer the remaining open points.
 - · Draft of the paper and material should be circulated in advance
 - Characterization of the chip prototypes
 - participation to test beams in the last months
 - BabyMoss (first weeks of September) → with also training for testing
 - Final MLR1 OPAMP test beam (in October)
 - Procurement of instrumentations for our lab
 - 2 new 55Fe sources (from Progetto Quasimodo) received
 - 2 new DAQ boards received
 - 1 BabyMoss and 1 raiser board will arrive tomorrow (others eventually later)
 - Procurement of new power supplies (with funds from Quasimodo)→ order to be placed

- ITS3 + other projects
 - - Layout «SVT-1» --> ITS3: 3 L0, 3 L1 + SVT: 4 L0, 4 L1
 - Layout «SVT-3» --> ITS3: 3 L2
 - Layout «NA60+» --> PixelChamber: 16 + Na60+: 4

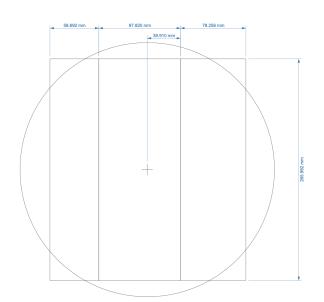
--> 7 wafers

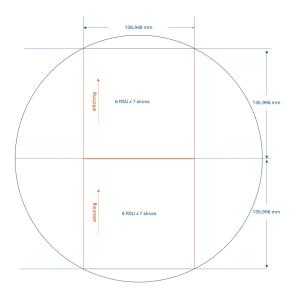
--> 3 wafers

--> 10 wafers



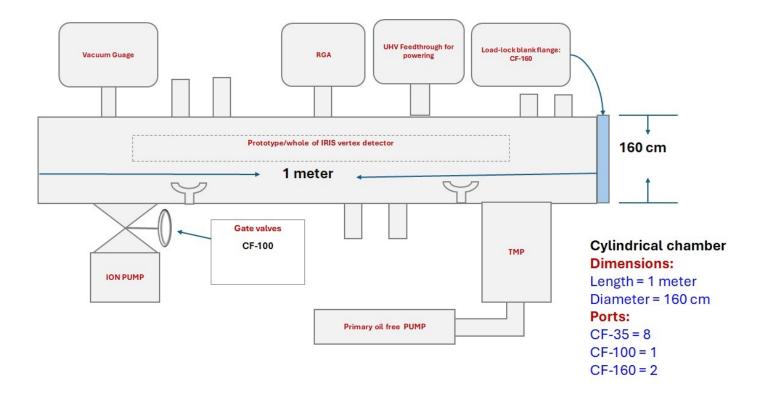
Layout 1





• Next year we should procure either ER2 pad wafers or dummy chips from blank wafers with Cr/Al metal deposition

- ALICE 3
 - - Cosimo should place the order the next week at the latest.



- ALICE 3
 - discussion in Krakow (Upgrade week) on how to setup «projects» with Work Pakage substructure

https://indico.cern.ch/event/1415726/timetable/

Inner Tracker

- Chip design (needs two branches, and two WP leaders dedicated to VD/ML)
 - Common items:
 - Common blocks
 - Serial powering
 - · Front-end optimisation
 - VD-ML optimisation:
 - · Development of a small pitch, high radiation tolerance chip
 - Adaptation and configuration for ML
 - Two independent reticle assemblies (VD and ML)
 - Target: submission end of 2025/beginning of 2026
- Characterisation (shared)
 - Characterisation of chips and modules in vacuum
 - Testing of existing prototypes at high radiation level
 - Characterisation of bent chips
- Sensor integration (VD focussed)
 - Lightweight module ('MAPS foil')
 - 2.5d / 3d integration of powering and data transmission
 - ML integration (for lightweight version)

- ALICE 3
 - discussion in Krakow (Upgrade week) on how to setup «projects» with Work Pakage substructure

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Inner Tracker

- ML module/stave design (→ will evolve into production)
- Mechanics and integration (two WP leaders dedicated to VD/ML synergy with OT)
 - VD: retractable in-vacuum mechanics
 - ML: bent or planar module and staves
 - Global integration and interfaces to beam pipe and iTOF/OT
 - Cooling architectures
- Readout and power supply services (two WP leaders dedicated to VD and ML)
 - Vacuum integration
 - Radiation hardness
 - Serial powering
- Physics performance and response simulation (common to OT)
- Detector Control System (not starting yet)
- Calibration and data quality assurance (VD needs to start first)
 - Alignment procedures for the IRIS

